

Second Biennial 3D Power Electronics Integration and Manufacturing Symposium Charts the Future of Integrative Packaging Technologies

Registration is now open for the International 3D-PEIM-18 Symposium, June 25-27, 2018, University of Maryland, College Park, MD



MENDHAM, NJ— March 21, 2018 — [The Power Sources Manufacturers Association](#) (PSMA) is pleased to announce that the second biennial International Symposium on 3D Power Electronics Integration and Manufacturing ([3D-PEIM-18](#)) will be held June 25-27, 2018, on the

campus of the University of Maryland. Following on the success of the inaugural event in 2016, 3D-PEIM-18 brings together a group of world-class experts representing a range of disciplinary perspectives to advance development of future 3D power electronics systems.

The symposium encompasses additive, embedded, co-designed and integrative packaging technologies. Sessions will address mechanical, materials, reliability and manufacturability issues in deploying small, smart power-dense components and modules.

The 3D-PEIM-18 symposium is underwritten by the PSMA as part of its ongoing commitment to educate and inform the power electronics industry. Other supporting organizations include: CALCE/University of Maryland, Virginia Tech, North Carolina State University, and the IEEE Electronics Packaging Society.

“Power electronic professionals from all disciplines are encouraged to attend this important forum showcasing developments in 3D packaging, thermal management, systems integration and manufacturing of integrated power electronic systems,” said Professor Patrick McCluskey, the Conference General Chair. “A highly dedicated, multidisciplinary technical committee of active PE researchers from industry, government labs and universities has recruited leading experts to speak on a wide range of relevant topics,” added 3D-PEIM-18 Technical Program Chair, Professor Guo-Quan Lu. “I am sure our symposium will provide a great learning and interactive experience for all attendees.”

In addition to the technical sessions and tutorials, the symposium will also feature table-top exhibits during the breaks, lunch periods and evening networking sessions. On the last day of the symposium, attendees are invited on a guided tour of the Center for Advanced Life Cycle Engineering (CALCE) at the University of Maryland.

Please go to www.3D-PEIM.org for additional information and registration details.

About PSMA

[PSMA](#) is a non-profit professional organization with the two-fold objective of enhancing the stature and reputation of its members and their products, and improving their technological power sources knowledge. Its aim is to educate the electronics industry, academia, government and industry communities as to the applications and importance of all types of power sources and conversion devices.

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